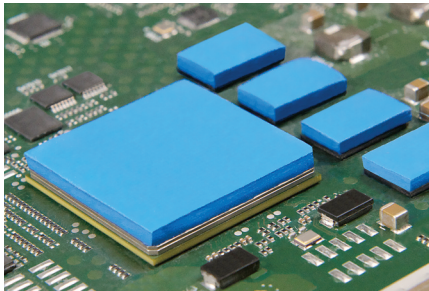


Gap Pad® HC 3.0

High-Compliance, Thermally Conductive, Low Modulus Material

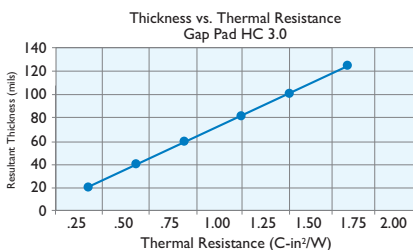
Features and Benefits

- Thermal Conductivity: 3.0 W/m-K
- High-compliance, low compression stress
- Fiberglass reinforced for shear and tear resistance



Gap Pad® HC 3.0 is a soft and compliant gap filling material with a thermal conductivity of 3.0 W/m-K. The material offers exceptional thermal performance at low pressures due to a unique 3.0 W/m-K filler package and low-modulus resin formulation. The enhanced material is ideal for applications requiring low stress on components and boards during assembly. Gap Pad® HC 3.0 maintains a conformable nature that allows for quick recovery and excellent wet-out characteristics, even to surfaces with high roughness and/or topography.

Gap Pad® HC 3.0 is offered with natural inherent tack on both sides of the material, eliminating the need for thermally-impeding adhesive layers. The top side has minimal tack for ease of handling. Gap Pad® HC 3.0 is supplied with protective liners on both sides.



TYPICAL PROPERTIES OF GAP PAD HC 3.0

PROPERTY	IMPERIAL VALUE	METRIC VALUE	TEST METHOD	
Color	Blue	Blue	Visual	
Reinforcement Carrier	Fiberglass	Fiberglass	—	
Thickness (inch) / (mm)	0.010 to 0.125	0.254 to 3.175	ASTM D374	
Inherent Surface Tack	2	2	—	
Density (Bulk Rubber) (g/cc)	3.1	3.1	ASTM D792	
Heat Capacity (J/g-K)	1.0	1.0	ASTM E1269	
Hardness (Bulk Rubber) (Shore 00) (4)	15	15	ASTM D2240	
Young's Modulus (psi) / (kPa) (1)	16	110	ASTM D575	
Continuous Use Temp (°F) / (°C)	-76 to 392	-60 to 200	—	
ELECTRICAL				
Dielectric Breakdown Voltage (Vac) (3)	5000	5000	ASTM D149	
Dielectric Constant (1000 Hz)	6.5	6.5	ASTM D150	
Volume Resistivity (Ohm-meter)	10 ¹⁰	10 ¹⁰	ASTM D257	
Flame Rating	V-O	V-O	U.L. 94	
THERMAL				
Thermal Conductivity (W/m-K) (2)	3.0	3.0	ASTM D5470	
THERMAL PERFORMANCE vs. STRAIN				
Deflection (% strain)		10	20	30
Thermal Impedance (°C-in²/W) 0.040" (2)		0.57	0.49	0.44
1) Young's Modulus, calculated using 0.01 in/min. step rate of strain with a sample size of 0.79 inch² after 5 minutes of compression at 10% strain on a 1mm thickness material.				
2) The ASTM D5470 test fixture was used. The recorded value includes interfacial thermal resistance. These values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.				
3) Typical value at 20 mil.				
4) Thirty second delay value on Shore 00 hardness scale.				

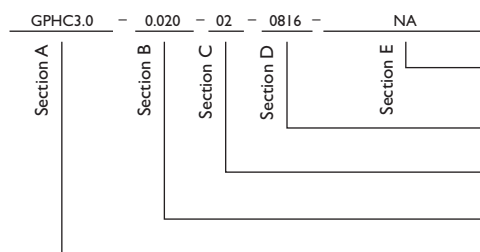
Typical Applications Include:

- Telecommunications
- ASICs and DSPs
- Consumer electronics
- Thermal modules to heat sinks

Configurations Available:

- Sheet form and die-cut parts

Building a Part Number



Standard Options

example

NA = Selected standard option. If not selecting a standard option, insert company name, drawing number, and revision level.

0816 = Standard sheet size 8" x 16", or
00 = custom configuration

02 = Natural tack, both sides (With Fiberglass)

Standard thicknesses available: 0.010", 0.015", 0.020", 0.030", 0.040", 0.060", 0.080", 0.100", 0.125"

GPHC3.0 = Gap Pad HC 3.0 Material with fiberglass

Note: To build a part number, visit our website at www.bergquistcompany.com.

BERGQUIST

www.bergquistcompany.com

The Bergquist Company -
North American Headquarters
18930 West 78th Street
Chanhassen, MN 55317
Phone: 800-347-4572
Fax: 952-835-0430

The Bergquist Company -
European Headquarters
Netherlands
Phone: 31-35-5380684
Fax: 31-35-5380295

The Bergquist Company -
Asia Headquarters
Hong Kong
Ph: 852-2690-9296
Fax: 852-2690-3408

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PDS_GC_HC3_0415

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<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9